Apogee™ Mechancial Debonder

With DataStream™ Technology

The Cee® Apogee™ debonder is designed to separate bonded wafers. The Apogee™ debonder system enables use of materials that broaden the thermal budget while maintaining very low-stress room temperature debonding.

Cost Effective Equipment

Serving the Semiconductor Industry Since 1987

BENEFITS

- In-house debonding of thinned device wafers
- Device wafer debonding on film frame
- Full-color, 7-inch touch screen display
- DataStream™ technology as the standard interface
- Force logging

DIMENSIONS

- 635 mm W x 914 mm D x 1842 mm H (25" W x 36" D x 72.5" H)
- Machine weight: 153 kg (337 lb)
- Shipping weight: 300 kg (661 lb)

UTILITIES

- Voltage: 90-264 V AC; 50/60Hz
- Power: 365 Watts
- Vacuum: <35 kPa (>20 in Hg)
- N_2 or CDA: 0.35 kPa (55 psi)

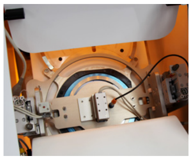
OTHER SPECIFICATIONS

- Substrate sizes (round): 50 mm to 300 mm
- Force range: 0 to 100 N (1 to 22 lb)
- Excess force sensing: Failsafe error recovery

Debonding Tool Platform Reliability	
Total Throughput	Up to 20 WPH
Yield	> 98%
Wafer Size	50 mm to 300 mm
Operating Temperature	Room Temperature

Front View With Loading Tray Open

Top View With Lid Open



Side View

CostEffectiveEquipment.com
(573) 364-0300

DATASTREAM™ TECHNOLOGY: CONNECTING THE SEMICONDUCTOR INDUSTRY

DataStream™ technology gives you access to all of your connected Apogee™ manufacturing equipment in one place to track, access, and modify your systems via a website or mobile app. This technology will give manufacturers the ability to process and visualize data in real time and search and export that data into a number of different formats.

Real-Time Process Information

- Constant feedback of process information for monitoring critical process parameters
- Streamlined interface between different tool types
- Visual cues on process status & health

Advanced Recipe Creation

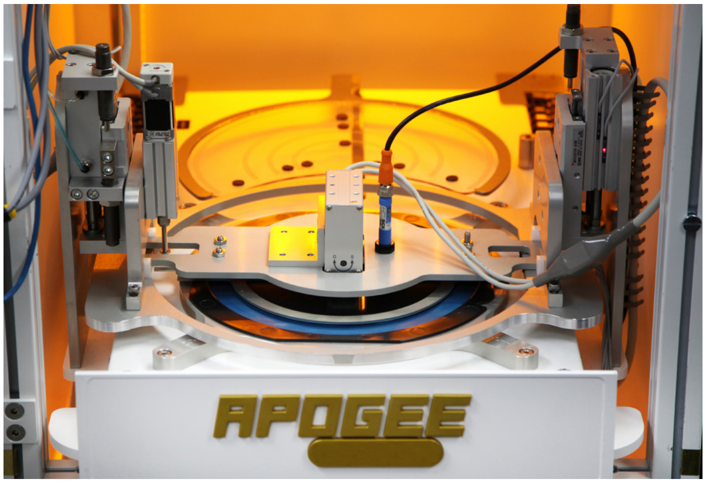
- Seamless switching between basic and advanced recipe creation methods
- Plain-English recipe translation
- Pre-defined process commands
- Unlimited process steps
- Unlimited recipe storage

Environmental Monitoring

- Monitoring of temperature & humidity allows for stricter control of critical processes
- Set preconditions and tolerances for monitored parameters
- On-screen, colored visual cues for deviation from controlled specs

Data Logging & Export

- Export data logs into commonly readable formats for further analysis and process troubleshooting
- Increase process efficiency
- Identify process control deviations
- Analyze multiple processes for best known method (BKM) development



Effective Date: 7/8/2016